

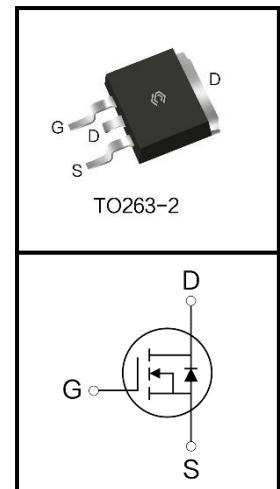
800V Super–Junction Power MOSFET

FEATURES

- Very low FOM $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- RoHS compliant
- Fast switching
- Integrate fast recovery diode

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information

Device	Package	Marking
CLB80R200MF	TO263-2	CLB80R200MF

Absolute Maximum Ratings at $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain–Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}	800	V
Continuous Drain Current	I_D	24	A
Continuous Drain Current $T_C = 100^\circ\text{C}$		14	
Pulsed Drain Current (note1)	I_{DM}	72	A
Gate–Source Voltage	V_{GSS}	± 30	V
Single Pulse Avalanche Energy (note2)	E_{AS}	172	mJ
Repetitive Avalanche Energy (note1)	E_{AR}	0.68	mJ
Power Dissipation	P_D	379	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction–Case	$R_{\theta JC}$	0.33	°C/W
Thermal Resistance, Junction–Ambient	$R_{\theta JA}$	62.5	

Electrical Characteristics $T_j = 25^\circ\text{C}$ unless otherwise specified						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	800	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 800\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	10	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 30\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	3.0	4.0	5.0	V
Drain-Source On-Resistance (Note3)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 12\text{A}$	--	0.17	0.2	Ω
Gate resistance	R_G	f = 1.0MHz open drian	--	1.3	--	Ω
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 100\text{V}, f = 250\text{kHz}$	--	2858	--	pF
Output Capacitance	C_{oss}		--	75	--	
Reverse Transfer Capacitance	C_{rss}		--	1.3	--	
Effective Output Capacitance (Energy Related)	$C_{\text{o(er)}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\sim 400\text{V}$	--	32	--	pF
Effective Output Capacitance (Time Related)	$C_{\text{o(tr)}}$		--	343	--	pF
Total Gate Charge	Q_g	$V_{\text{DD}} = 640\text{V}, I_D = 12\text{A}, V_{\text{GS}} = 0\sim 10\text{V}$	--	60	--	nC
Gate-Source Charge	Q_{gs}		--	15	--	
Gate-Drain Charge	Q_{gd}		--	24	--	
Gate Plateau Voltage	V_{pl}		--	5.9	--	V
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 400\text{V}, I_D = 12\text{A}, R_G = 25\Omega$	--	63	--	ns
Turn-on Rise Time	t_r		--	31	--	
Turn-off Delay Time	$t_{\text{d(off)}}$		--	228	--	
Turn-off Fall Time	t_f		--	40	--	
Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	24	A
Pulsed Diode Forward Current	I_{SM}		--	--	72	
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 12\text{A}, V_{\text{GS}} = 0\text{V}$	--	0.91	1.2	V
Reverse Recovery Time	t_{rr}	$V_R = 400\text{V}, I_F = 12\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	--	180	--	ns
Reverse Recovery Charge	Q_{rr}		--	0.97	--	μC
Peak Reverse Recovery Current	I_{rrm}		--	9	--	A

Notes

- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{\text{AS}} = 6\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega, L = 10\text{mH}$, Starting $T_J = 25^\circ\text{C}$
- Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Typ.Output Characteristics

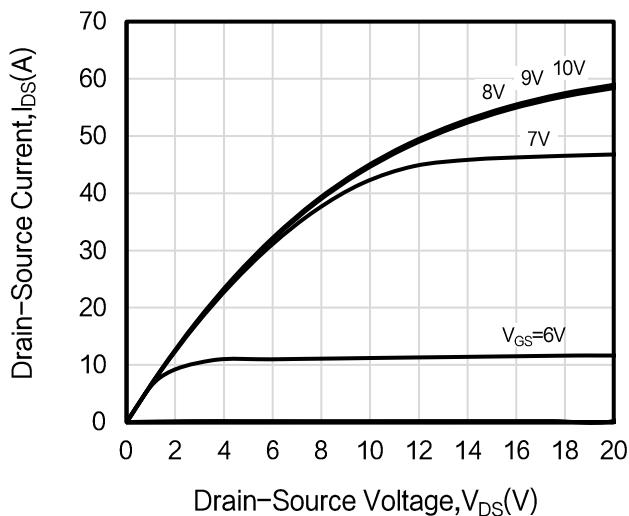


Figure 2. Transfer Characteristics

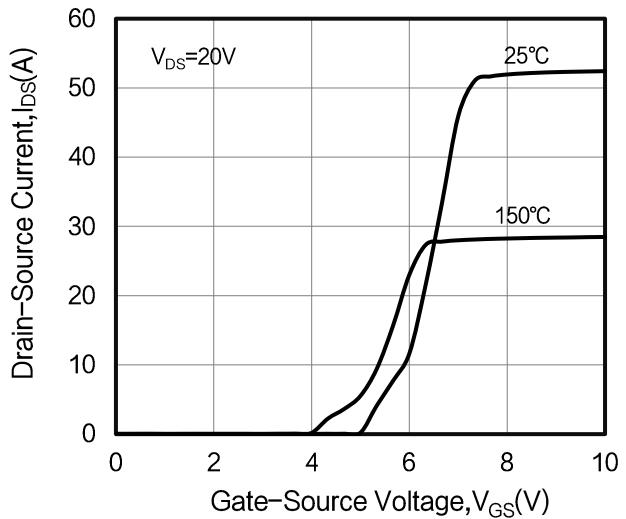


Fig.3 On-Resistance vs.Drain Current

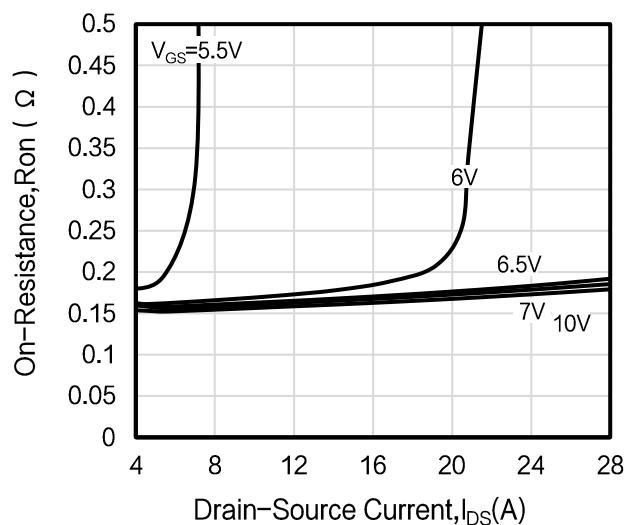


Fig.4 On-Resistance vs. Temperature

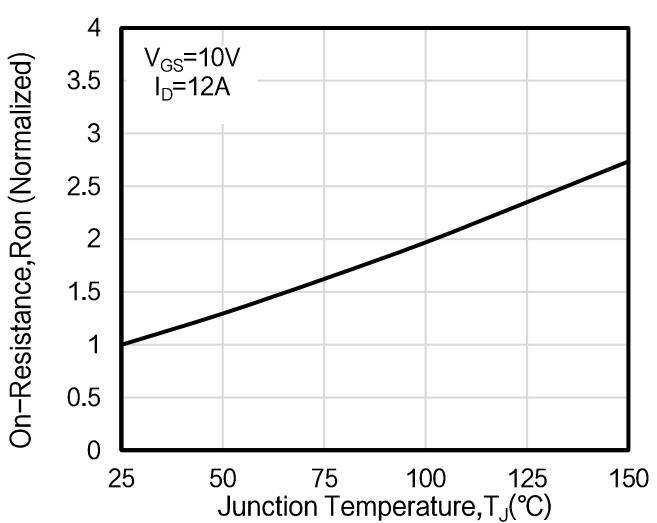


Figure 5. Body Diode Forward Voltage

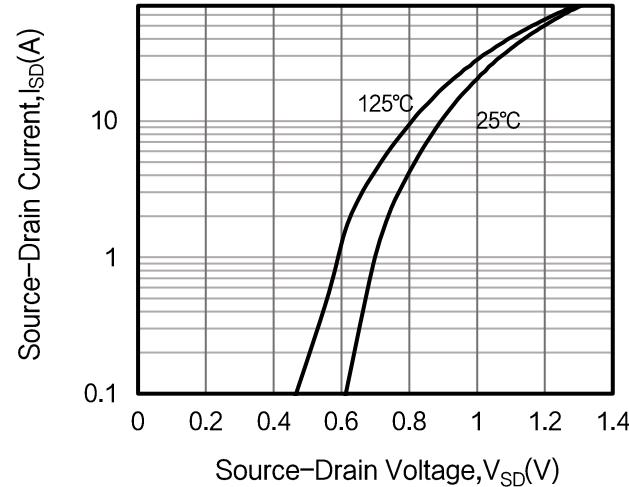
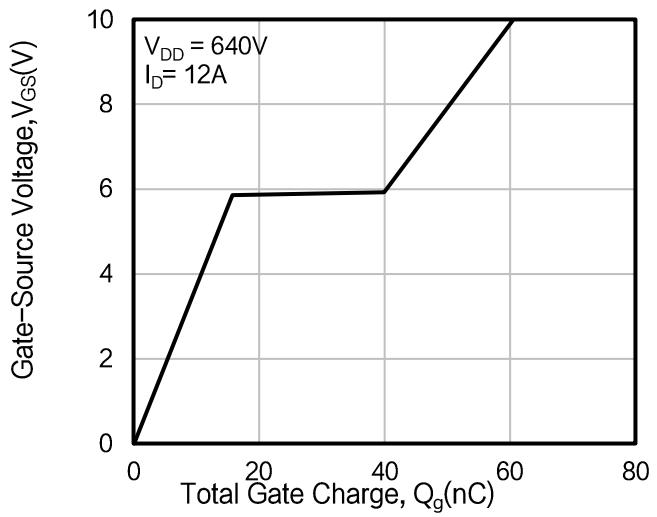


Figure 6. Gate Charge



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Breakdown Voltage vs.Temperature

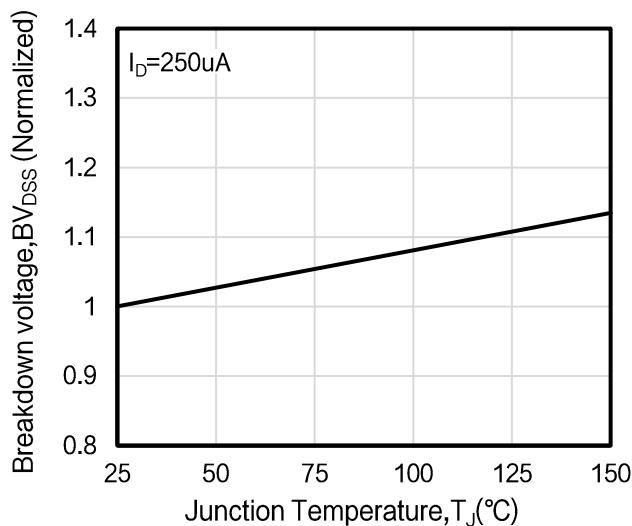


Fig.8 Capacitances

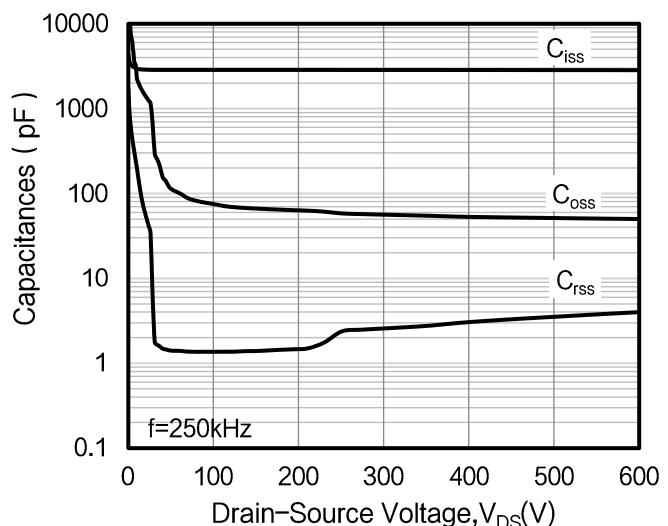


Fig.9 Coss Stored Energy

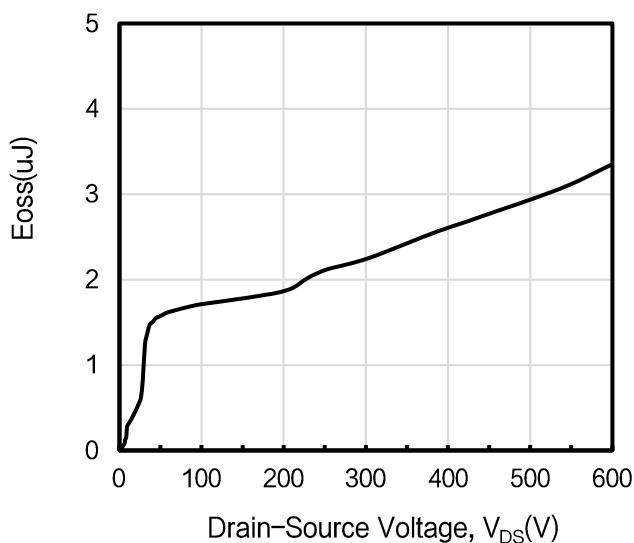


Figure10. Power Dissipation

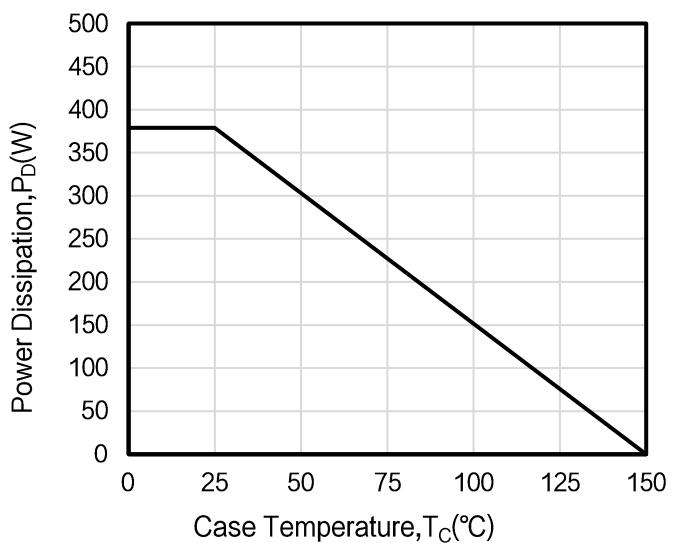


Figure 11. Transient Thermal Impedance

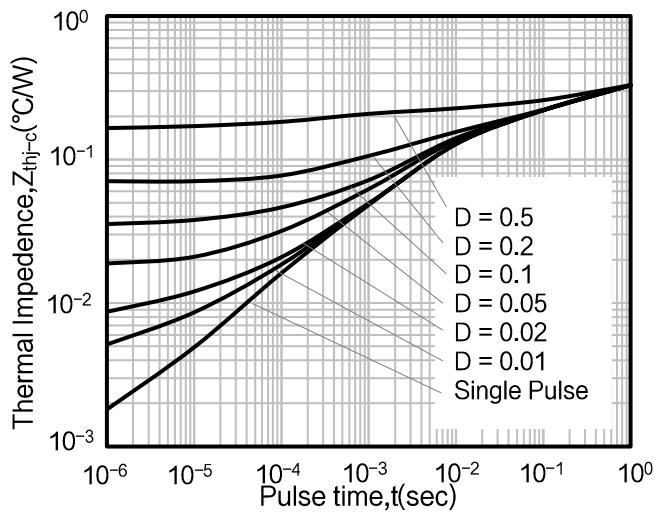


Figure 12. Safe Operation Area

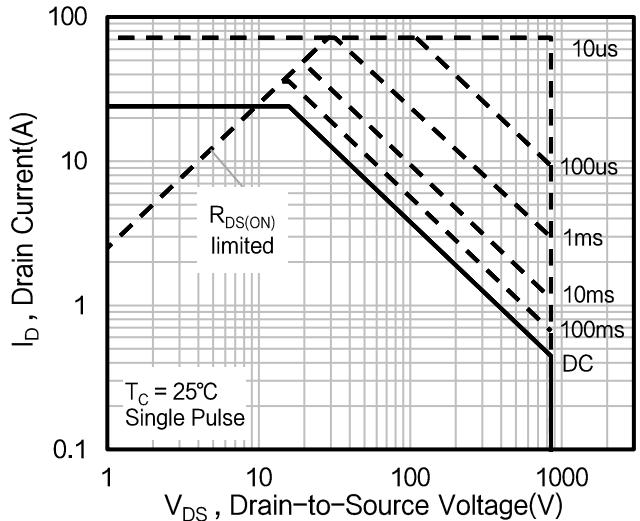


Figure A: Gate Charge Test Circuit and Waveform

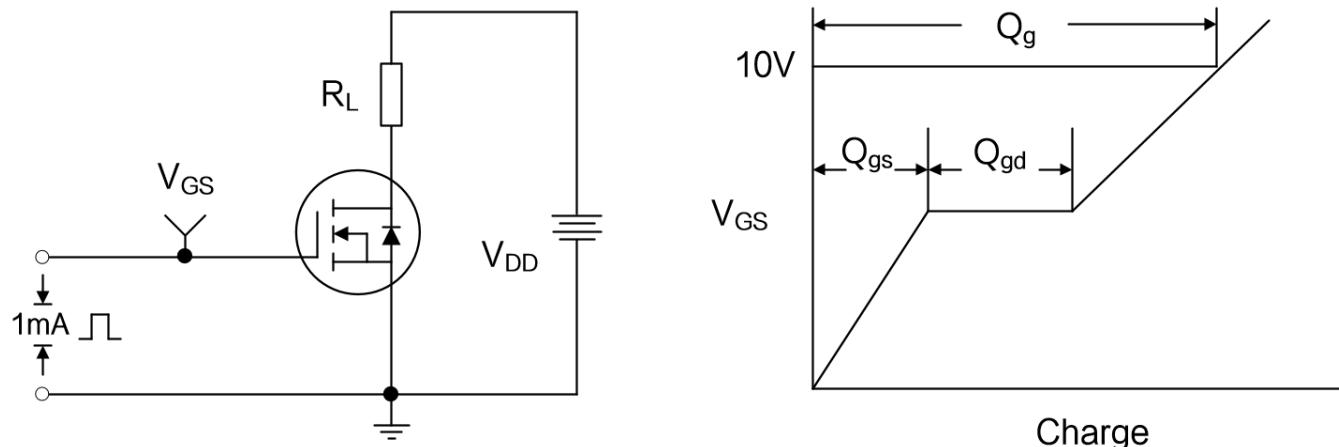


Figure B: Resistive Switching Test Circuit and Waveform

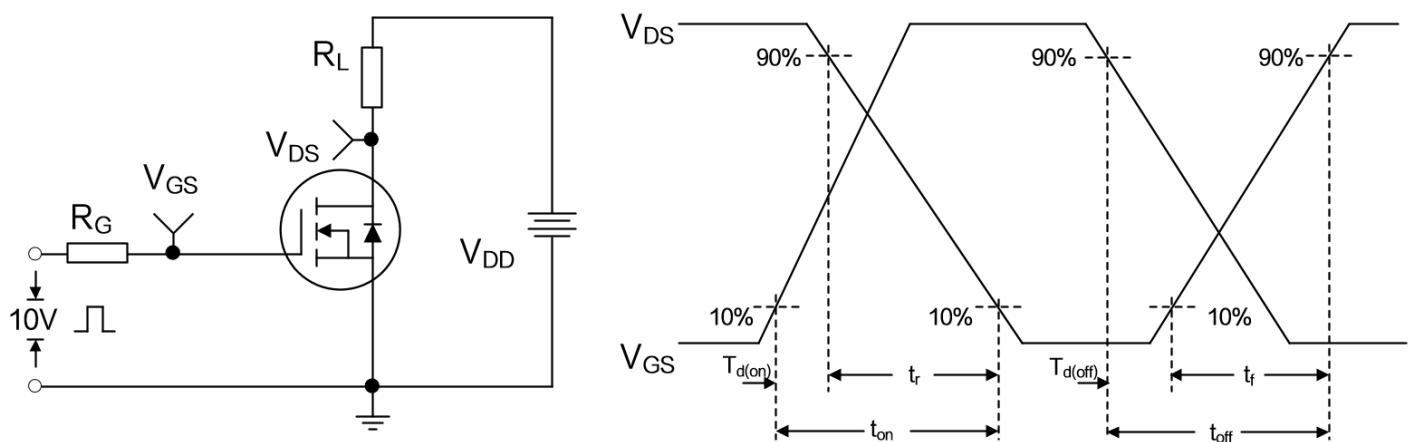
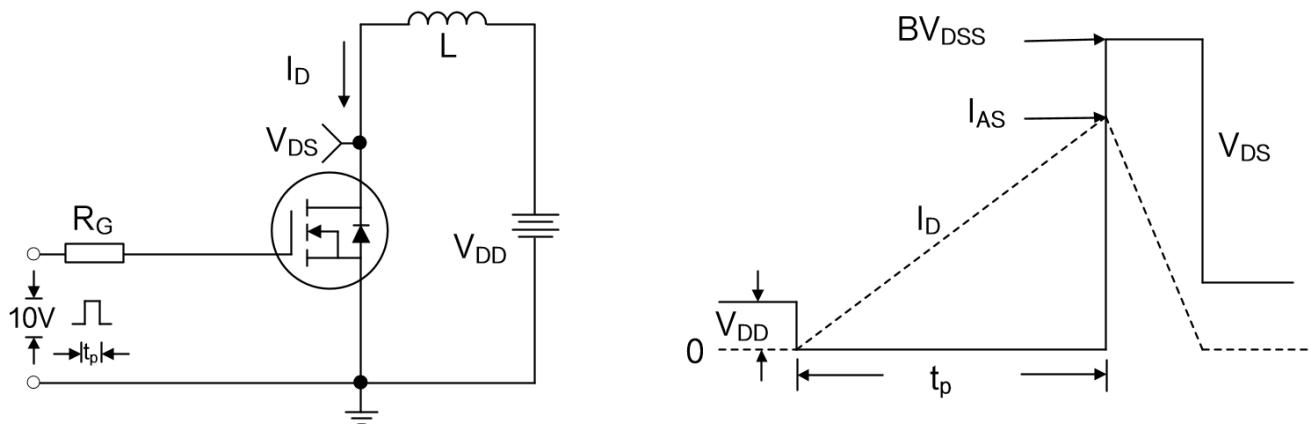
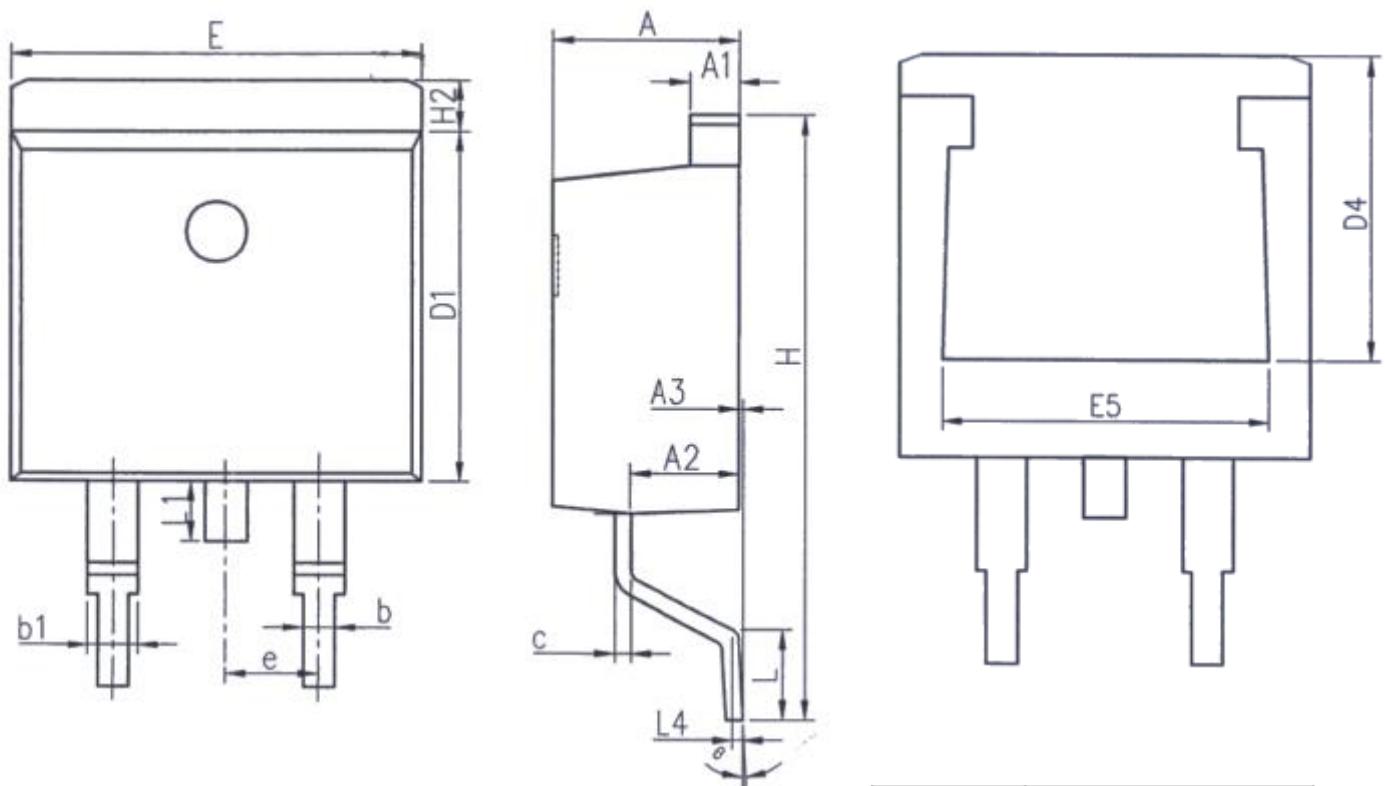


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



TO263-2



SYMBOLS	MILLIMETERS	
	MIN	MAX
A	4.37	4.77
A1	1.22	1.40
A2	2.49	2.89
A3	0.00	0.25
b	0.7	0.96
b1	1.17	1.47
c	0.30	0.53
D1	8.50	8.90
D4	6.60	-
E	9.86	10.36
E5	7.06	-
e	2.54 BSC	
H	14.70	15.50
H2	1.07	1.47
L	2.00	2.60
L4	025 BSC	
Φ	0°	9°

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